

#### **STG6684**

#### High isolation dual SPDT analog switch

#### **Features**

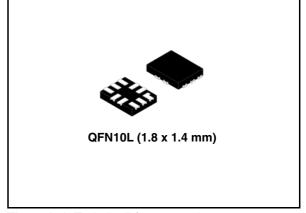
- Ultra high off-isolation:-80 dB (typ) at 1 Mhz
- Ultra low power dissipation:  $I_{CC} = 0.2 \mu A \text{ (max.)}$  at  $T_A = 85 \text{ °C}$
- R<sub>PEAK</sub> on T<sub>n</sub> = 1.30  $\Omega$  max (T<sub>A</sub> = 25 °C) at V<sub>CC</sub> = 4.3 V
- R<sub>PEAK</sub> on S<sub>n</sub> = 0.55  $\Omega$  max (T<sub>A</sub> = 25 °C) at V<sub>CC</sub> = 4.3 V
- Wide operating voltage range:V<sub>CC</sub> (opr) = 1.65 to 4.3 V single supply
- 4.3 V tolerant and 1.8 V compatible threshold on digital control input at V<sub>CC</sub> = 1.65 to 4.3 V
- Typical bandwidth (-3 dB) at 65 MHz on Sn channel, 58 MHz on the T<sub>n</sub> channel
- Latch-up performance exceeds 100 mA per JESD 78, Class II
- ESD performance exceeds JESD22 2000-V Human body model (A114-A)

#### **Description**

The STG6684 is a high-speed CMOS low voltage dual analog SPDT (single pole dual throw) switch or 2:1 multiplexer/de-multiplexer switch fabricated in silicon gate C<sup>2</sup>MOS technology.

The STG6684 is designed to operate from 1.65 to 4.3 V, making this device ideal for portable applications.

The SELn inputs are provided to control the switch operation. The switch Sn is ON (connected to common ports Dn) when the SELn input is held low and OFF (high impedance state exists between the two ports) when SELn is held high.



The switch Tn is "on" (connected to common port Dn) when the SELn input is held high and "off" (high impedance state exists between the two ports) when SELn is held low.

Additional key features are fast switching speed, break-before-make delay time and ultra low power consumption. All inputs and outputs are equipped with protection circuits against static discharge, giving them ESD immunity and transient excess voltage.

Table 1. Device summary

Order code	Package	Packaging
STG6684QTR	QFN10L (1.8 x 1.4 mm)	Tape and reel

January 2008 Rev 1 1/24

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www.Data STG6684<sup>m</sup> Pin settings

## 1 Pin settings

Figure 1. Pin connection (top through view)

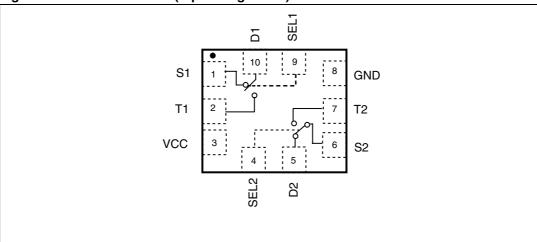


Table 2. Pin description

Pin number	Symbol	Name and function			
1	S1	Independent channel			
2	T1	Independent channel			
3	V <sub>CC</sub>	Positive supply voltage			
4	SEL2	Selection control			
5	D2	Common channel			
6	S2	Independent channel			
7	T2	Independent channel			
8	GND	Ground (0 V)			
9	SEL1	Selection control			
10	D1	Common channel			

www.Data Logic diagram STG6684

## 2 Logic diagram

Figure 2. Logic block diagram

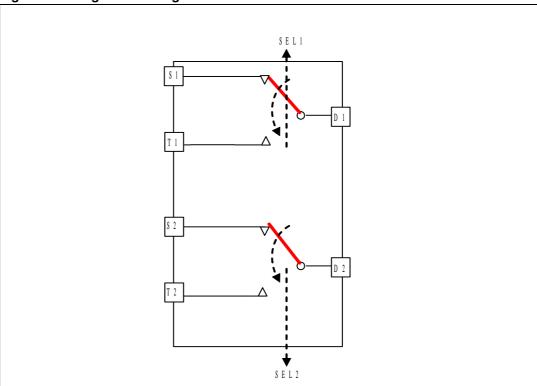


Table 3. Truth table

SELn	Switch Sn	Switch Tn		
L	Sn is connected to Dn	OFF <sup>(1)</sup>		
Н	OFF <sup>(1)</sup>	Tn is connected to Dn		

<sup>1.</sup> High impedance

www.Data STG6684<sup>m</sup> Maximum rating

#### 3 Maximum rating

Stressing the device above the rating listed in the "Absolute maximum ratings" table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability. Refer also to the STMicroelectronics SURE Program and other relevant quality documents.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	Supply voltage	-0.5 to 5.5	V
V <sub>I</sub>	DC input voltage	-0.5 to V <sub>CC</sub> + 0.5	V
V <sub>IC</sub>	DC control input voltage	-0.5 to 5.5	V
V <sub>O</sub>	DC output voltage	-0.5 to V <sub>CC</sub> + 0.5	V
I <sub>IKC</sub>	DC input diode current on control pin (V <sub>SEL</sub> < 0 V)	-50	mA
I <sub>IK</sub>	DC input diode current (V <sub>SEL</sub> < 0 V)	±50	mA
I <sub>OK</sub>	DC output diode current	±20	mA
Io	DC output current	±300	mA
I <sub>OP</sub>	DC output current peak (pulse at 1 ms, 10% duty cycle)	±500	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC V <sub>CC</sub> or ground current	±100	mA
P <sub>D</sub>	Power dissipation at T <sub>A</sub> =70 °C <sup>(1)</sup>	1120	mW
T <sub>STG</sub>	Storage temperature	-65 to 150	°C
T <sub>L</sub>	Lead temperature (10 sec)	300	°C

<sup>1.</sup> Derate above 70 °C by 18.5 mW/°C

www.Datas Maximum rating STG6684

#### 3.1 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Value	Unit	
V <sub>CC</sub>	Supply voltage		1.65 to 4.3	V
VI	Input voltage		0 to V <sub>CC</sub>	٧
V <sub>IC</sub>	Control input voltage		0 to 4.3	٧
V <sub>O</sub>	Output voltage		0 to V <sub>CC</sub>	V
T <sub>op</sub>	Operating temperature		-40 to 85	°C
dt/dv	Input rise and fall time control	V <sub>CC</sub> = 1.65 V to 2.7 V	0 to 20	no/\/
αι/αν	input	V <sub>CC</sub> = 3.0 V to 4.3 V		ns/V

www.Data STG6684<sup>m</sup> Electrical characteristics

### 4 Electrical characteristics

Table 6. DC specifications

						Value			
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	TA	= 25	°C	-40 to	85 °C	Unit
		(V)		Min	Тур	Max	Min	Max	
		1.65 –1.95		0.65 V <sub>CC</sub>			0.65 V <sub>CC</sub>		
.,	High level input	2.3 –2.5		1.2			1.2		.,
V <sub>IH</sub>	voltage	2.7 -3.0		1.3			1.3		V
		3.3 –3.6		1.4			1.4		
		4.3		1.5			1.5		
		1.65 –1.95				0.25		0.25	
		2.3 –2.5				0.25		0.25	
$V_{IL}$	Low level input voltage	2.7 -3.0				0.25		0.25	V
	vollago	3.3 –3.6				0.30		0.30	
		4.3				0.40		0.40	
		4.3			1.10	1.3		1.5	
	R <sub>PEAK</sub> , Switch T <sub>n</sub> ON resistance	3.6	$V_S = 0 \text{ V to } V_{CC}$ $I_S = 100 \text{ mA}$		1.15	1.4		1.6	Ω
R <sub>PEAK</sub> , Tn		3.0			1.25	1.5		1.8	
	resistance	2.7	is – 100 ma		1.35	1.6		1.9	
		1.8			2.20	2.9		3.5	
		4.3			0.45	0.55		0.62	
		3.6			0.48	0.58		0.65	
R <sub>PEAK,</sub> Sn	Switch S <sub>n</sub> ON resistance	3.0	$V_S = 0 \text{ V to } V_{CC}$ $I_S = 100 \text{ mA}$		0.51	0.62		0.70	Ω
On	resistance	2.7	is – 100 ma		0.54	0.70		0.80	
		1.8			0.84	1.10		1.30	
		4.3			10				
	ON resistance	3.6	_		14				
$\Delta R_{ON,}$ Tn	match between	3.0	V <sub>S</sub> at R <sub>PEAK</sub> I <sub>S</sub> = 100 mA		14				mΩ
	Tn channels <sup>(1)</sup>	2.7	is – 100 ma		15				
		1.8			30				
		4.3			7				
	ON resistance	3.6	_		7				mΩ
$\Delta R_{ON,}$ Sn	match between	3.0	V <sub>S</sub> at R <sub>PEAK</sub>		8				
OII	Sn channels <sup>(1)</sup>	2.7	I <sub>S</sub> = 100 mA		9				
		1.8			12				

Table 6. DC specifications

	Value								
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T	= 25	°C	-40 to	85 °C	Unit
		(•)		Min	Тур	Max	Min	Max	
		4.3			0.45	0.50		0.55	
	ON resistance	3.6			0.45	0.50		0.55	
R <sub>FLAT,</sub> Tn	flatness for Tn	3.0	$V_S = 0$ to $V_{CC}$ $I_S = 100 \text{ mA}$		0.50	0.55		0.60	Ω
	channels <sup>(2)</sup>	2.7			0.55	0.60		0.70	
		1.8			1.10	1.70		2.00	
	ON resistance	4.3			0.15	0.20		0.20	
	flatness for Sn channels <sup>(2)</sup>	3.6			0.15	0.20		0.20	
R <sub>FLAT,</sub> Sn	RFLAT,	3.0	$V_S = 0$ to $V_{CC}$ $I_S = 100 \text{ mA}$		0.15	0.20		0.20	Ω
Oil		2.7	15 - 100 1121		0.15	0.20		0.20	
		1.8			0.35	0.55		0.66	
I <sub>OFF</sub>	OFF state leakage current (Tn), (Sn), (Dn)	4.3	V <sub>S</sub> = 0.3 or 4 V			±0.1		±1	μΑ
I <sub>SEL</sub>	SEL leakage current	0 –4.3	V <sub>SEL</sub> = 0 to 4.3 V			±0.05		±1	μА
I <sub>CC</sub>	Quiescent supply current	1.65 –4.3	V <sub>SEL</sub> = V <sub>CC</sub> or GND			±0.05		±0.2	μА
	Quiescent		V <sub>SEL</sub> = 1.65 V		±37	±50		±100	
I <sub>CCLV</sub>	supply current low voltage	4.3	V <sub>SEL</sub> = 1.80 V		±33	±40		±50	μΑ
	driving		V <sub>SEL</sub> = 2.60 V		±12	±20		±30	

<sup>1.</sup>  $\Delta R_{ON} = R_{ON(max)} - R_{ON(min)}$ .

<sup>2.</sup> Flatness is defined as the difference between the maximum and minimum value of on-resistance as measured over the specified analog signal ranges.

**Table 7.** AC electrical characteristics ( $C_L = 35 \text{ pF}, R_L = 50 \Omega, t_r = t_f \le 5 \text{ ns}$ )

				<b>F</b> · , · ·	_	Value	1		
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T,	<sub>A</sub> = 25	°C	-40 to	85 °C	Unit
		(-)		Min	Тур	Max	Min	Max	
		1.65 —1.95			0.45				
t <sub>PLH,</sub>	Propagation	2.3 —2.7			0.45				no
t <sub>PHL</sub>	delay	3.0 —3.3			0.30				ns
		3.6 -4.3			0.30				
		1.65 —1.95	V <sub>S</sub> = 0.8 V		120				
tou	Turn-ON time	2.3 —2.7			65	85		90	ne
t <sub>ON</sub>	Turn-ON time	3.0 —3.3	V <sub>S</sub> = 1.5 V		42	55		65	ns
		3.6 —4.3			40	55		65	
		1.65 —1.95	V <sub>S</sub> = 0.8 V		45				
+.	Turn-OFF	2.3 —2.7	V <sub>S</sub> = 1.5 V		18	30		40	- ns
t <sub>OFF</sub>	time	3.0 -3.3			16	30		40	
		3.6 -4.3			15	30		40	
		1.65 —1.95		2	18				
	Break-before- make time	2.3 —2.7	$C_L = 35 \text{ pF}$ $R_L = 50 \Omega$	2	10				ns
t <sub>D</sub>	delay	3.0 —3.3	$V_{S} = 1.5 \text{ V}$	2	8				113
		3.6 —4.3		2	6				
		1.65 —1.95			43				
	Charge	2.3 —2.7	$C_L = 100 \text{ pF}$ $R_L = 1 \text{ M}\Omega$		51				pC
Q	injection	3.0 -3.3	$V_{GEN}^- = 0 V$ $R_{GEN} = 0 \Omega$		51				
		3.6 —4.3	GLIN 5		49				

**Table 8.** Analog switch characteristics ( $C_1 = 5 \text{ pF}, R_1 = 50 \Omega, T_{\Delta} = 25 ^{\circ}\text{C}$ )

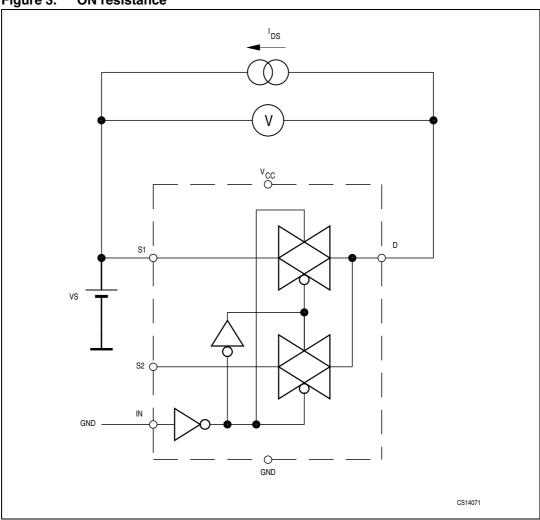
Table 8.	Analog switch characteristics ( $C_L = 5 \text{ pF}, R_L = 50 \Omega, T_A = 25 \text{ °C}$ )  Value								
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T,	<sub>A</sub> = 25	°C	-40 to	85 °C	Unit
		( )		Min	Тур	Max	Min	Max	
OIRR <sub>Tn</sub>	Off isolation for switch	1.65 —4.3	$V_S$ =1 $V_{RMS}$ , f=1 MHz, $R_L$ = 50 $\Omega$		-80				dB
- 111	T1,T2		$V_S$ =1 $V_{RMS}$ , f = 10 MHz, $R_L$ = 50 $\Omega$		-60				<b>G.</b>
OIRR <sub>Sn</sub>	Off isolation for switch	1.65 —4.3	$V_{S} = 1 V_{RMS},$ f = 100  kHz $RL = 50 \Omega$		-66				dB
Ontrign	S1, S2	1.00 —4.0	$V_{S}=1 \ V_{RMS},$ $f = 1 \ MHz$ $R_{L} = 50 \ \Omega$		-45				ub.
Xtalk <sub>Sn</sub>	Crosstalk between S1	1.65 — 4.3	V <sub>S</sub> =1 V <sub>RMS</sub> , f = 1 MHz Signal = 0 dBm		-90				dB
Mangn	and S2	1.00 — 4.0	V <sub>S</sub> =1 V <sub>RMS</sub> , f = 10 MHz Signal = 0 dBm		-69				dB
	Crosstalk between T1	1.65 — 4.3	V <sub>S</sub> =1 V <sub>RMS</sub> , f = 1 MHz Signal = 0 dBm		-85				dB
XtalkTn	and T2	1.00 — 4.0	V <sub>S</sub> =1 V <sub>RMS</sub> , f = 10 MHz Signal = 0 dBm		-74				QD.
THD <sub>Sn</sub>	Total harmonic distortion	2.3 — 4.3	$\begin{aligned} & f = 20 \text{ Hz to } 20 \\ & \text{kHz} \\ & R_L = 600 \ \Omega, \\ & C_L = 50 \ \text{pF} \\ & V_{\text{IN}} = 2 \ V_{\text{P-P}} \\ & V_{\text{DC}} = V_{\text{CC}} / 2 \end{aligned}$		0.01				%
BW <sub>Tn</sub>	-3dB bandwidth for switch T1, T2	1.65 — 4.3	$R_L = 50 \Omega$ Signal = 0 dBm		58				MHz
BW <sub>Sn</sub>	-3dB bandwidth for switch S1,S2	1.65 — 4.3	$R_L = 50 \Omega$ Signal = 0 dBm		65				MHz

						Value			
Symbol	Parameter	V <sub>CC</sub> (V)	Test condition	T,	<sub>A</sub> = 25	°C	-40 to	85 °C	Unit
		(-)		Min	Тур	Max	Min	Max	
C <sub>SEL</sub>	Control pin input capacitance		V <sub>CC</sub> = 0 V		9				
C <sub>ON,Tn</sub>	Tn port capacitance when the switch is enabled	3.3	f = 1 MHz		113				
C <sub>ON,Sn</sub>	Sn port capacitance when the switch is enabled	3.3	f = 1 MHz		88				pF
C <sub>OFF,Tn</sub>	Tn port capacitance when the switch is disabled	3.3	f = 1 MHz		85				
C <sub>OFF,Sn</sub>	Sn port capacitance when the switch is disabled	3.3	f = 1 MHz		40				

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## 5 Test circuit

Figure 3. ON resistance



www.Data STG6684<sup>m</sup> Test circuit

Figure 4. OFF leakage

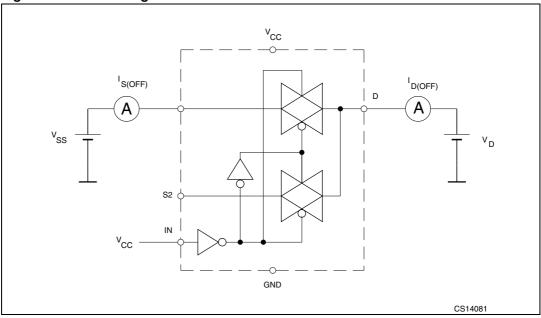
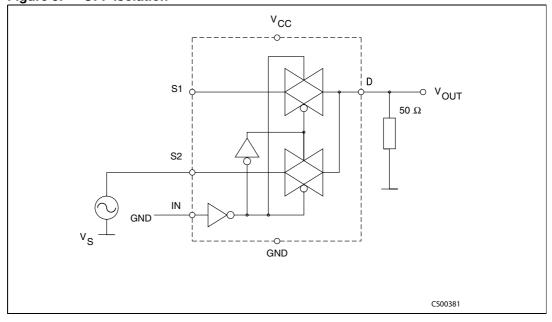


Figure 5. OFF isolation



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Figure 6. Bandwidth

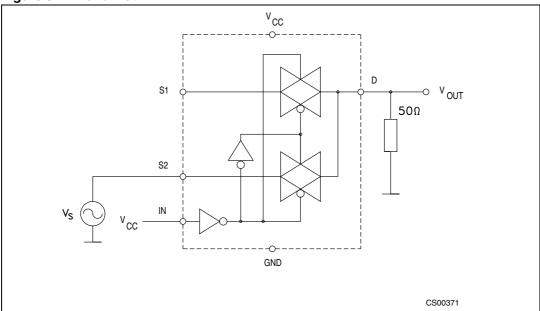
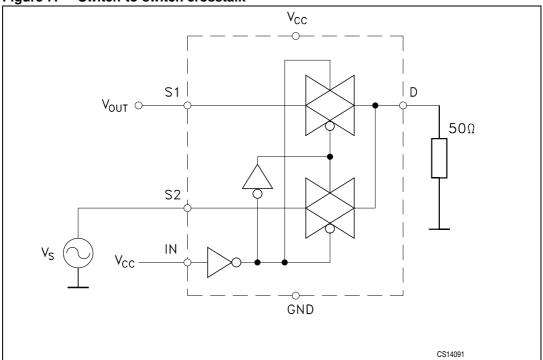
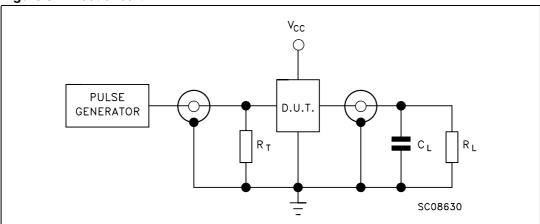


Figure 7. Switch-to-switch crosstalk



www.DataSTG6684<sup>m</sup> Test circuit

Figure 8. Test circuit



- 1.  $C_L = 5/35$  pF or equivalent (includes jig and probe capacitance)
- 2.  $R_L = 50 \Omega$  or equivalent
- 3.  $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

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Figure 9. Break-before-make time delay

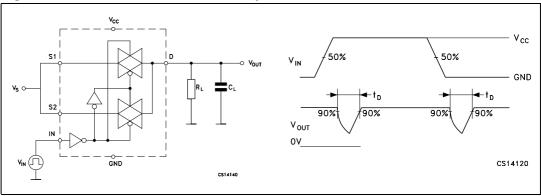


Figure 10. Switching time and charge injection (V<sub>GEN</sub> = 0, R<sub>GEN</sub> = 0  $\Omega$ , R<sub>L</sub> = 1 M $\Omega$ , C<sub>L</sub> = 100 pF)

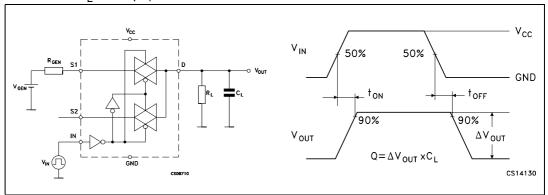
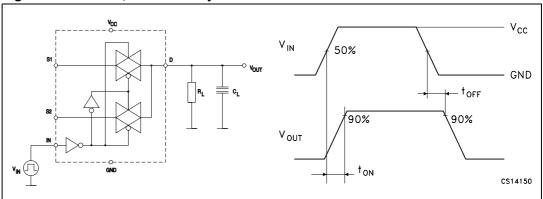


Figure 11. Turn on, turn off delay time



www.Data STG6684<sup>TI</sup> Application diagram

# 6 Application diagram

Figure 12. Application diagram

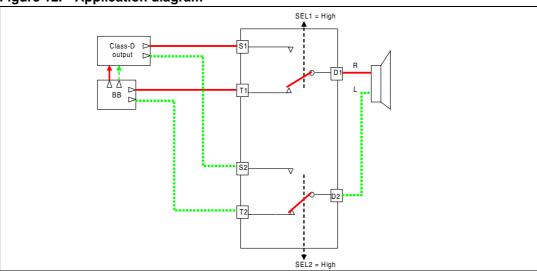
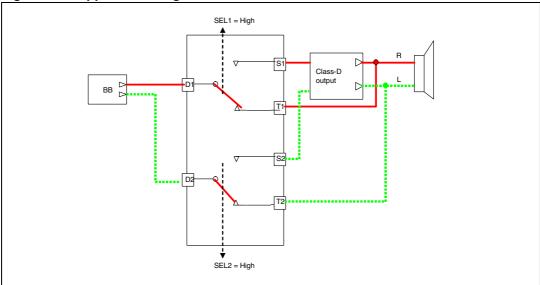


Figure 13. Application diagram



#### Package mechanical data 7

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a Lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

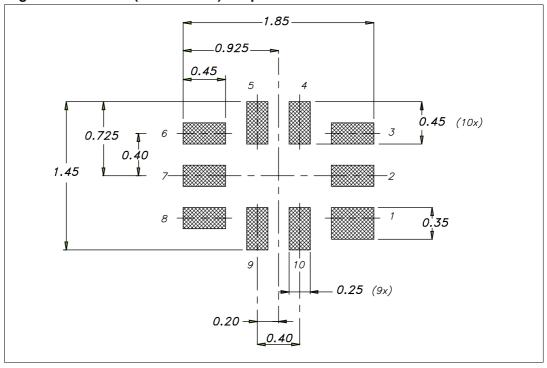
BOTTOM VIEW PIN 1 ID (10x) b (10x) // 0.05 C -A3 SEATING PLANE c 0.05 C 10x LEADS COPLANARITY E/2 8 10 PIN 1 ID D/2 TOP VIEW 7936408 Rev.D

Figure 14. QFN10L (1.8 x 1.4 mm) package outline

Table 2. QFN10L(1.8 x 1.4 mm) mechanical data

Symbol		Millimeters	
Symbol	Min	Тур	Max
А	0.45	0.50	0.55
A1	0	0.02	0.05
A3		0.127	
b	0.15	0.20	0.25
D	1.75	1.80	1.85
E	1.35	1.40	1.45
е		0.40	
L	0.35	0.40	0.45

Figure 15. QFN10L (1.8 x 1.4 mm) footprint recommendations



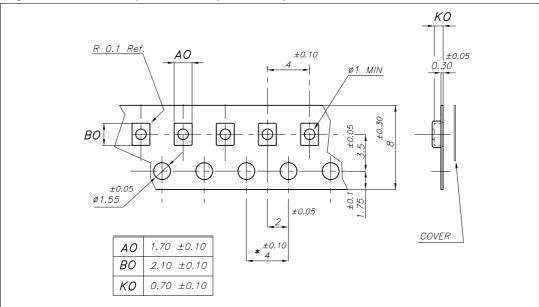


Figure 16. QFN10L (1.8 x 1.4 mm) carrier tape

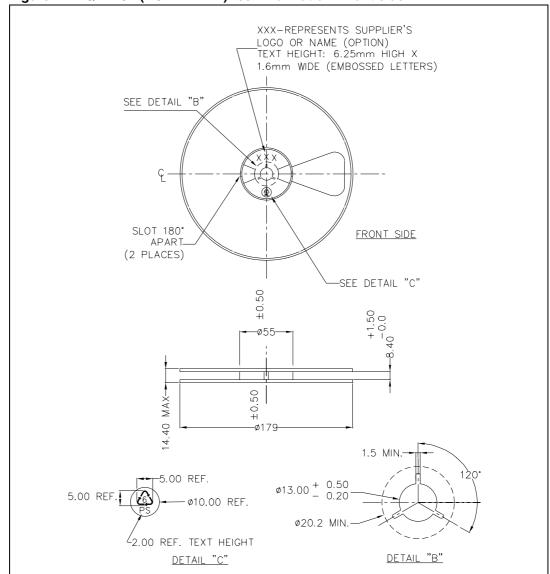


Figure 17. QFN10L (1.8 x 1.4 mm) reel information - front side

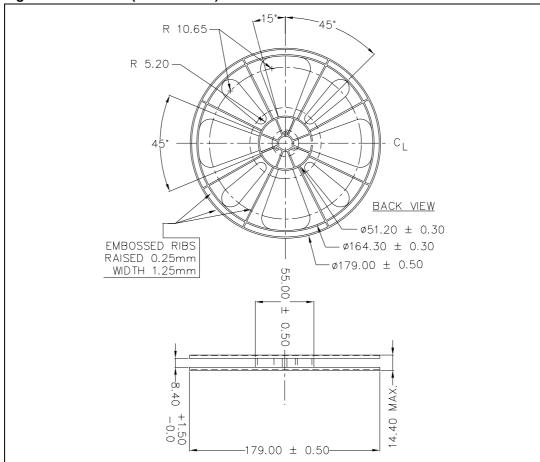


Figure 18. QFN10L(1.8 x 1.4 mm) reel information - back view

www.Data STG6684<sup>m</sup> Revision history

## 8 Revision history

Table 9. Document revision history

Date	Revision	Changes
9-Jan-2008	1	Initial release.

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